

Board File Name: blufi_poe.PcbDoc
 Design Name: blWifi_poe

Hole Count: 894
 Via Count: 841
 Pad Count: 1034

Board Material: FR408
 Number of Layers: 4
 Copper Weight: 1 Oz
 Finished Board Thickness: 0.8 mm
 Min Trace: 5mil
 Min Space: 4mil

Soldermask type: LPI BLUE
 Pad finish: ENIG
 Silkscreen Color: WHITE

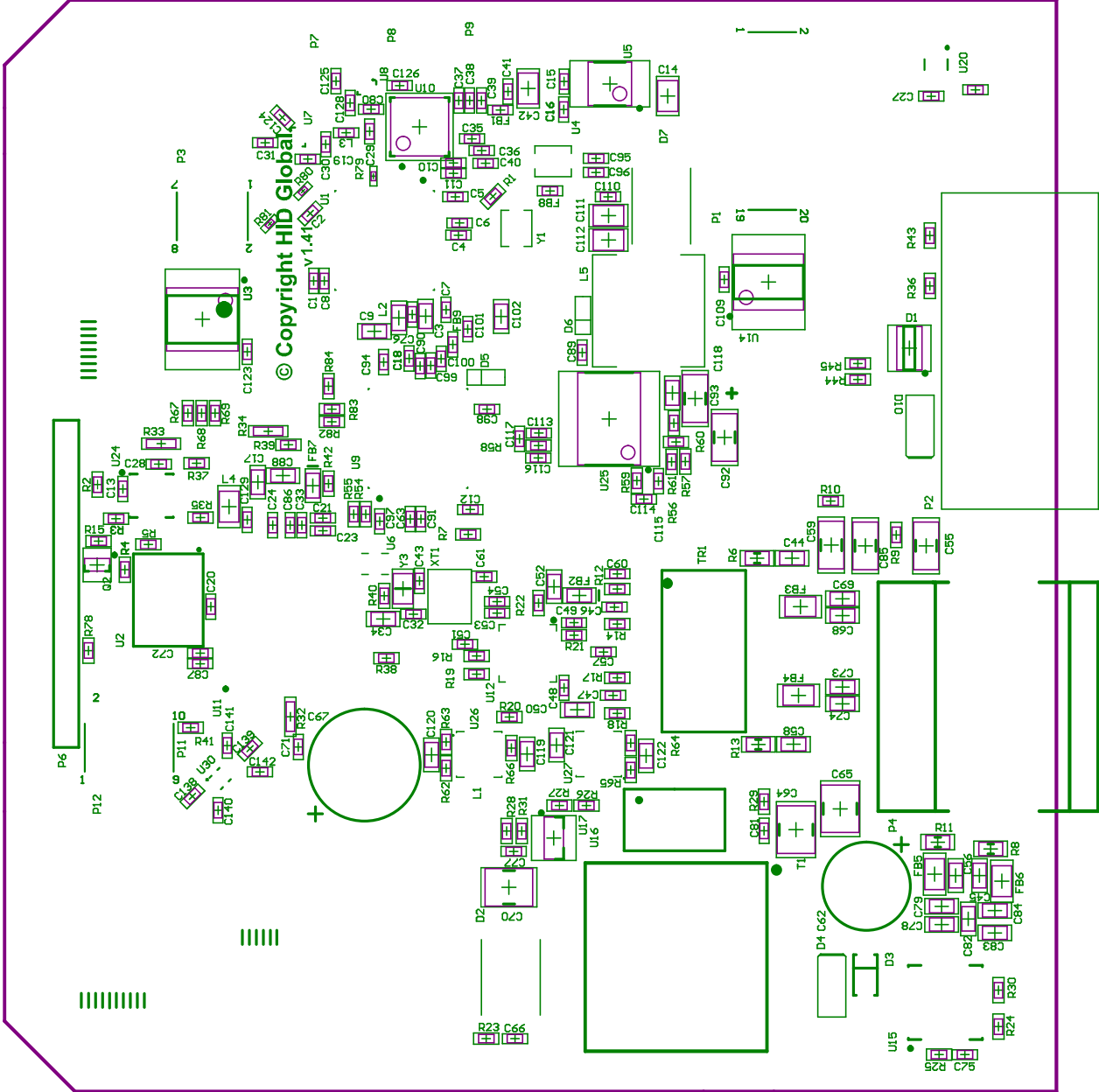
Minimum Via Size: Drill 10mil Dia 20mil

Files:
 Top Layer: GTL
 Top Soldermask: GTS
 Top Paste: GTP
 Top Silkscreen: GTO
 Signal 1: G1
 Signal 2: G2
 Bottom Layer: GBL
 Bottom Soldermask: GBS
 Bottom Paste: GBP
 Bottom Silkscreen: GBO

Board Outline: GM1 cut according to this layer
 Drill: TXT Top-Bottom

Documentation: PDF

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.40mil | 3.5 | |
| 1 | Top Layer | | 1.40mil | | |
| | Dielectric 1 | FR408 | 5.10mil | 3.65 | |
| 2 | Signal Layer 1 | | 1.40mil | | |
| | Dielectric 3 | FR408 | 16.00mil | 4.03 | |
| 3 | Signal Layer 2 | | 1.40mil | | |
| | Dielectric 2 | FR408 | 5.10mil | 3.65 | |
| 4 | Bottom Layer | | 1.40mil | | |
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Top Paste: GTP

Top Silkscreen: GTO

Signal 1: G1

Signal 2: G2

Bottom Layer: GBL

Bottom Soldermask: GBS

Bottom Paste: GBP

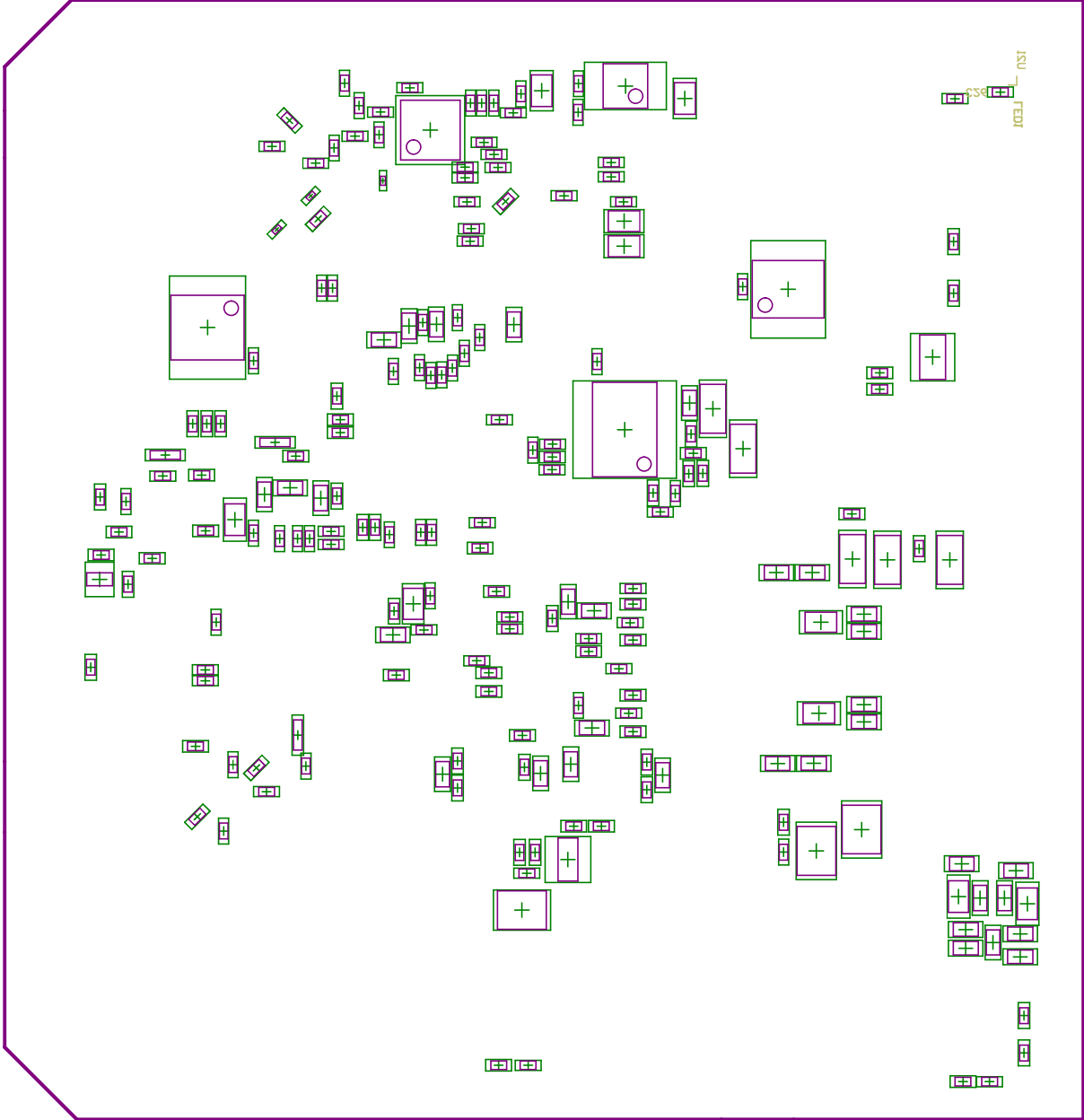
Bottom Silkscreen: GBO

Board Outline: GM1 cut according to this layer

Drill: TXT Top-Bottom

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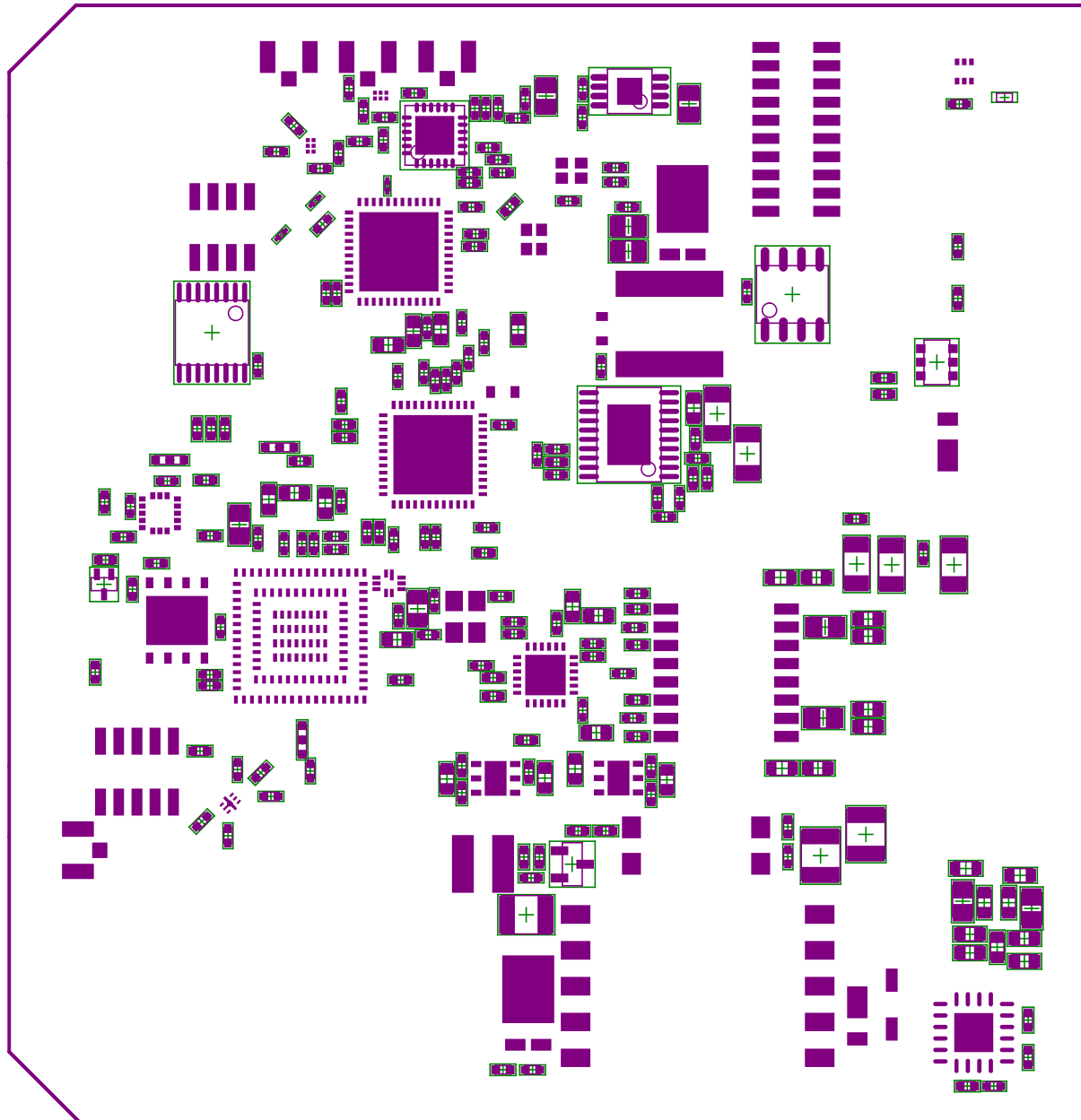
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Bottom Soldermask: GBS

Bottom Paste: GBP

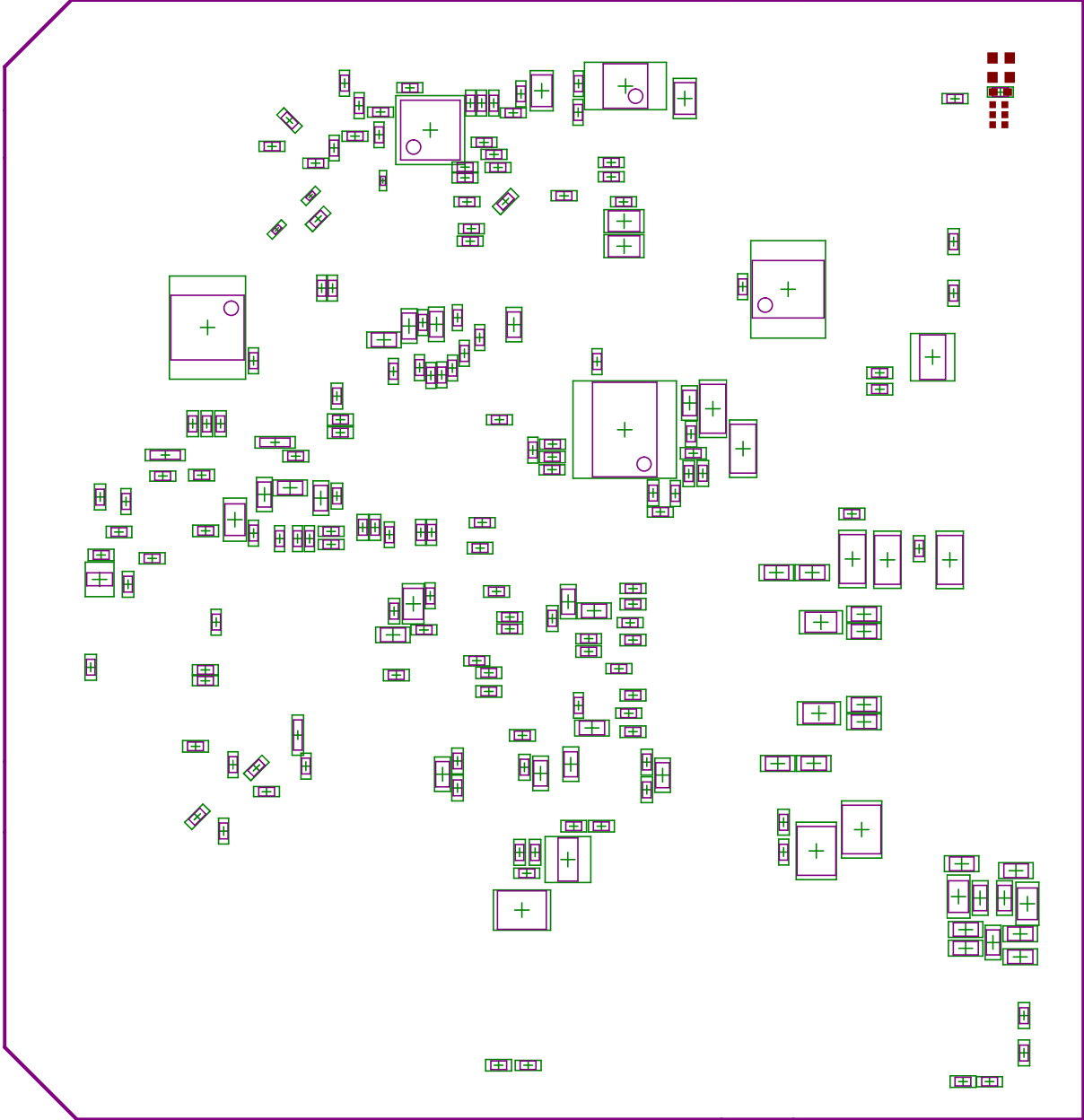
Bottom Silkscreen: GBO

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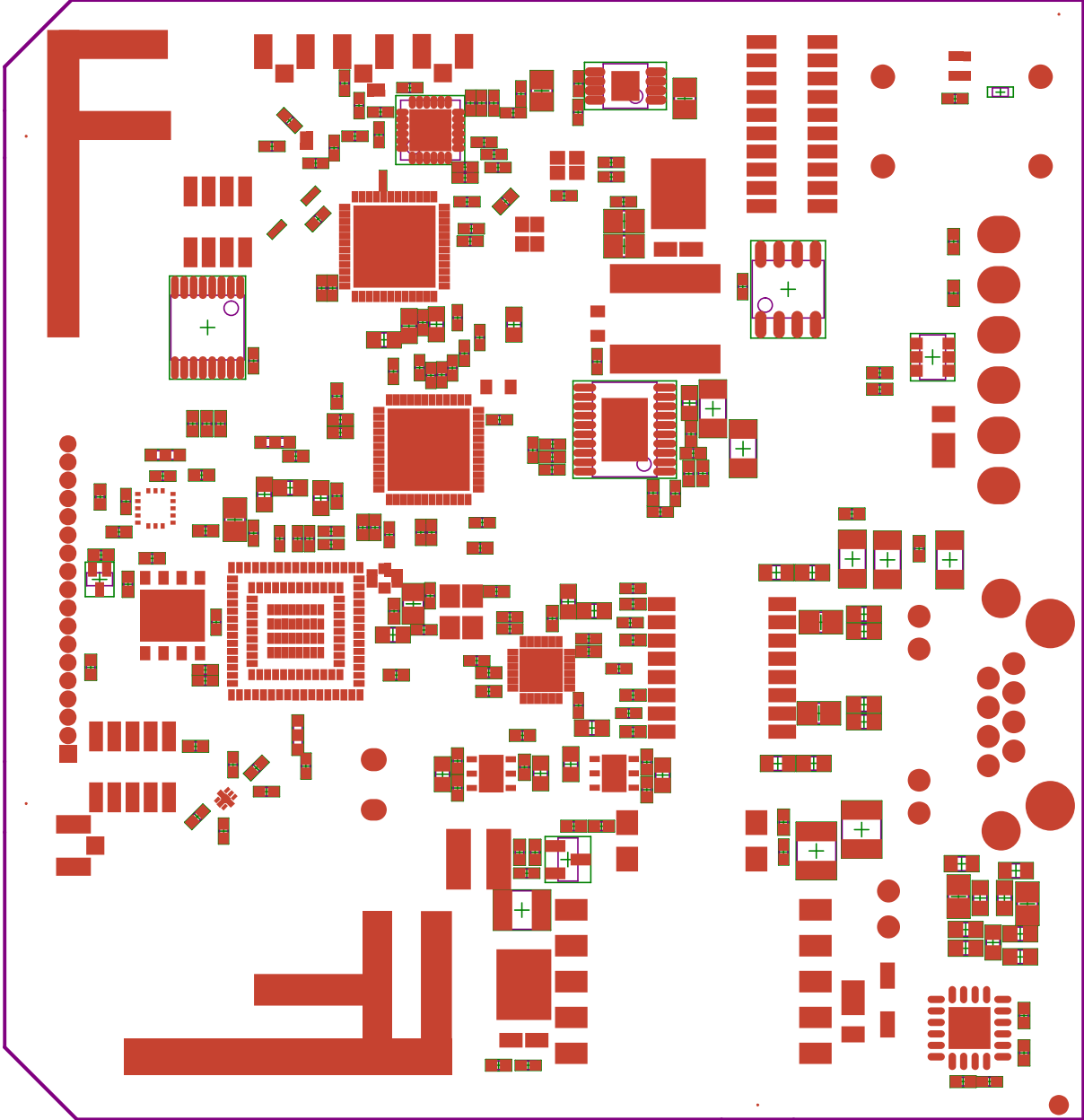
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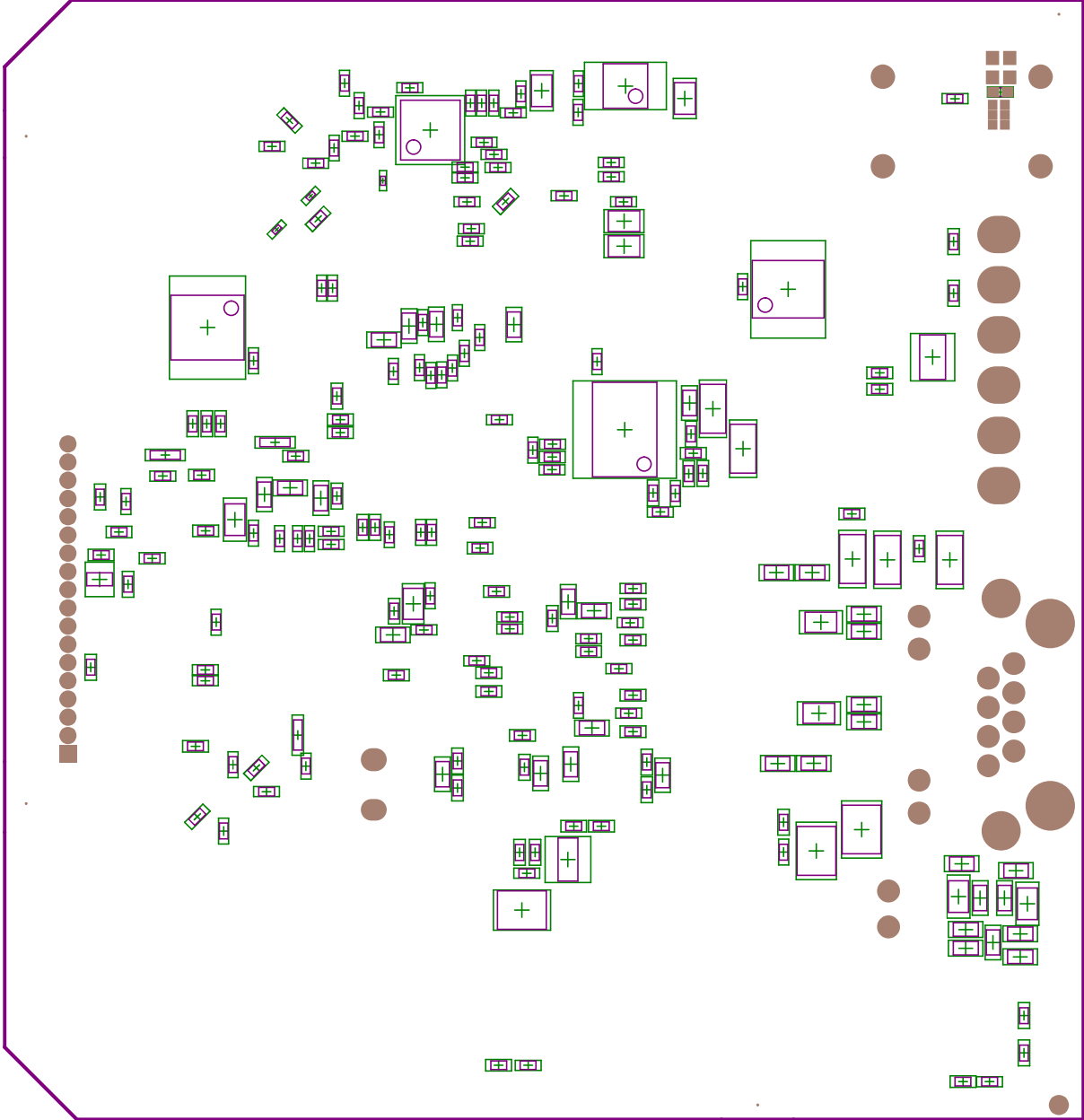
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